As a below named inventor, I hereby declare that.

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled <u>PROCESS FOR PRODUCTION OF SEMICONDUCTOR SUBSTRATE</u>

invention children i ROCLBS FOR I RODUCTION	OF SEMICONDUCTOR SUBSTRATE
	, the specification of which is
X attached hereto. was filed on	
as Application No	and was amended on
(if applicable).	

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR §1.56.

(Vac/No)

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

		(163/110)
Application No.	Filed (Day/Mo./Yr.)	Priority Claimed
39389	March 10, 1994	Yes
. 45441	March 6, 1995	Yes
260100	October 6, 1995	Yes
41709	February 28, 1996	Yes
	39389 45441 260100	39389 March 10, 1994 45441 March 6, 1995 260100 October 6, 1995

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Application No.	Filed (Day/Mo./Yr.)	Status (Patented/Pending/Abandoned)
08/401,237	03/09/1995	Abandoned
08/863,717	05/27/1997	Patented
09/161,775	09/29/1998	Pending
08/729,722	10/07/1996	Patented
09/212,432	12/16/1998	Patented
09/734,667	12/13/2000	Pending
08/807,604	02/27/1997	Patented
09/840,895	04/25/2001	Pending
09/933,711	08/22/2001	Pending

I hereby appoint the practitioners associated with the firm and Customer Number provided below to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and direct that all correspondence be addressed to the address associated with that Customer Number:

FITZPATRICK, CELLA, HARPER & SCINTO Customer Number: 05514

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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